

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shui-Tien Lin</td> <td>11/03/2005</td> </tr> <tr> <td>Shin-Rung Lu</td> <td>11/11/2005</td> </tr> <tr> <td>Yi-Chuan Lo</td> <td>11/03/2005</td> </tr> </tbody> </table>		Name	Execution Date	Shui-Tien Lin	11/03/2005	Shin-Rung Lu	11/11/2005	Yi-Chuan Lo	11/03/2005
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Shui-Tien Lin	11/03/2005								
Shin-Rung Lu	11/11/2005								
Yi-Chuan Lo	11/03/2005								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.								
Street Address:	No. 8, Li-Hsin Rd. 6								
Internal Address:	Science-Based Industrial Park								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11193126</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11193126				
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Application Number:	11193126								
CORRESPONDENCE DATA									
Fax Number:	(214)200-0853								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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NAME OF SUBMITTER:	David M. O'Dell								
Total Attachments: 2 source=assignment#page1.tif									

CH \$40.00 11193126

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|---------------|----|---|
| (1) | Shui-Tien Lin | of | 2F, No. 58, Lane 59, Chaiciao Road
Hsin-Chu, 300, Taiwan, R.O.C. |
| (2) | Shin-Rung Lu | of | 8F, No. 185, Wen-Yi Street
Chu-Pei City, Hsin-Chu, Taiwan, R.O.C. |
| (3) | Yi-Chuan Lo | of | No. 14, Alley 1, Lane 188, Xinxiang Street
Hsin-Chu, 300, Taiwan, R.O.C. |

have invented certain improvements in

**A SYSTEM AND METHOD FOR PHOTOLITHOGRAPHY
IN SEMICONDUCTOR MANUFACTURING**

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X on July 29, 2005 and assigned application number 11/193,126; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Shui-Tien Lin

Residence Address: 2F, No. 58, Lane 59, Chaiciao Road
Hsin-Chu, 300 Taiwan, R.O.C.
Taiwan, R.O.C.

Dated: 11/3/2005

Shui-Tien Lin
Inventor Signature

Inventor Name: Shin-Rung Lu

Residence Address: 8F, No. 185, Wen-Yi Street
Chu-Pei City, Hsin-Chu, Taiwan, R.O.C.
Taiwan, R.O.C.

Dated: 11/11/2005

Shin-Rung Lu
Inventor Signature

Inventor Name: Yi-Chuan Lo

Residence Address: No. 14, Alley 1, Lane 188, Xinxiang Street
Hsin-Chu, 300 Taiwan, R.O.C.
Taiwan, R.O.C.

Dated: 11/3/2005
Yi-Chuan Lo

Yi-Chuan Lo
Inventor Signature